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<p>(21) International Application Number: PCT/SG99/00005 (22) International Filing Date: 4 February 1999 (04.02.99) (71) Applicants (for all designated States except US): INSTITUTE OF MICROELECTRONICS [SG/SG]; 10 Science Park RD, #02-19/26 The Alpha, Singapore Science Park II, Singapore 117684 (SG). SIEMENS AG [DE/DE]; Paulsterstrasse 26, D-13629 Berlin (DE). (72) Inventors; and (75) Inventors/Applicants (for US only): UPPILI, Sridhar [US/SG]; 45A West Coast Way, Hin Sen Garden, Singapore 127012 (SG)/VICTOR, D., Samper [GB/SG]; 38 Dover Rise, Tower A, Dover Parkview #03-12, Singapore 138684 (SG). FOO, Pang, Dow [US/SG]; 8 Kent Ridge Road, Singapore 119217 (SG)/WAGENAAR, Dirk [DE/DE]; Bergmannstrasse 57, D-10961 Berlin (DE)/KAY, Krupka [DE/DE]; Aneasstrasse 12, D-12109 Berlin (DE)/SCHLAAK, Helmut [DE/DE]; Schwabstedter Weg 30A, D-13503 Berlin (DE). (74) Agent: LAWRENCE Y. D. HO &amp; ASSOCIATES; 30 Bideford RD., #07-01 Thongsia Building, Singapore 229922 (SG).</p>		<p>(81) Designated States: CA, CN, IN, JP, KR, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).  Published With international search report.</p>
<p>(54) Title: MICRO-RELAY</p> <p>(57) Abstract</p> <p>A microstructure relay comprising an s-shaped support member is provided. The s-shape support member creates over-travel in the relay in order to produce high contact force and low contact resistance over the lifetime of the relay. Compressive and tensile stress-inducing layers on appropriate parts of the support member induce it to bend as desired.</p>		

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